

Question 15

Q: Can Femtet analyze substrate warping caused by heat?

A: Yes, Femtet can do it in the thermal-stress coupled analysis.

The substrate can be deformed by the thermal strain that is generated from the temperature distribution resulting from the heating parts on it.

The substrate can also be deformed by the difference in thermal strain across the model after a change in temperature.

These deformations can be analyzed.

If the temperature distribution is uniform, the substrate deformation is solved using only the stress solver in the thermal load analysis.